

(1.27 mm) .050"

CLP SERIES

W-PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material:

Black Liquid Crystal Polymer Contact Material: Phosphor Bronze

Plating: Sn or Au over 50 μ" (1.27 μm) Ni

Current Rating (CLP/FTSH): 3.4 A per pin

(2 pins powered)

Voltage Rating:
280 VAC/395 VDC

Operating Temp Range: -55 °C to +125 °C

Insertion Depth:

Insertion Depth:
Top Entry = (1.40 mm) .055"
minimum, Bottom Entry =
(2.41 mm) .095" minimum
plus board thickness
DH Entry = (2.31 mm) .091"
to (2.67 mm) .105"
Normal Force:
60 grams (0.59 N) average
Max Cycles:
100 with 10 µ" (0.25 µm) Au
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (02-35) (0.15 mm) .006" max (36-50)* (.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

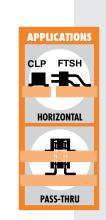


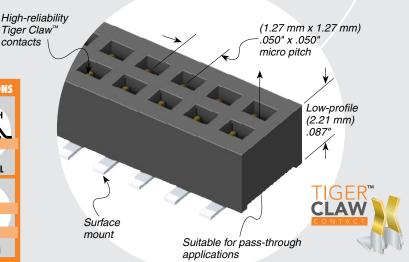
ALSO AVAILABLE (MOQ Required)

- · Single row
- · Other platings

Some sizes, styles and options are non-standard, non-returnable.

Mates with: TSH, FTS, FW





NO. PINS PLATING ROW **PER ROW OPTION OPTION**

No. of Positions x (1.27) .050 + (0.43) .017

000000

(0.41) || 01

-D

(0.41) .016 ->

OTHER OPTION

02 thru 50

100

⁹⁹ (1.27) .050 →

(3.43)

(3.56) .140

(7.11) .280

-DH

(4.57)(3.05)

.135[°]

PIN/ROW

04-15

16-50

180 .120

_F Gold flash on contact Matte Tin on tail

= 10 µ" (0.25 µm)

Gold on contact Matte Tin on tail

–G = 10 μ" (0.25 μm) Gold (-D only)

(1.27)

(2.29)

.090

(4.32)

.170

(1.40)

.055

-D = Double Row

–DH = Double

Horizontal (Requires FTSH-04 lead style)

(6.35)

250

(3.18)

125

P OPTION

.325

(0.89)

.035 DIA

-(7.00) .275 →

(2.54) .100

(3.07).121

-BE = Bottom Entry (Required for bottom entry applications)

= Alignment Pin (Not available with -PA option) (05, 06, 07, 08, 10, 12, 15, 20, 25, 30, 40 positions only) (-DH option and other sizes. Contact Samtec.)

–K

= (4.00 mm) .157" DIA Polyimide film Pick & Place Pad (5 positions minimum)

= Pick & Place Pad (5 positions min. –D only) (Not always necessary for auto placement. See Flex Processing.)

-PA

= Pick & Place Pad with Alignment Pin (-D only) (Not available with -A option)

-TR

= Tape & Reel

= Full Reel Tape & Reel Packaging (Must order maximum quantities per reel.
Contact Samtec for parts per reel)

If odd pins/row, alignment pins are on middle position on centerline of the part. If even pins/row, then alignment pins are between middle two positions. -PA OPTION Due to technical progress, all designs, specifications and components are subject to change without notice WWW.SAMTEC.COM